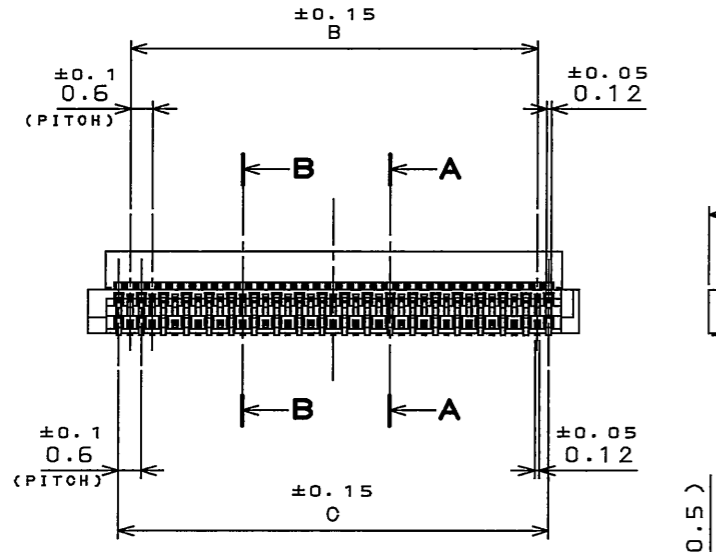
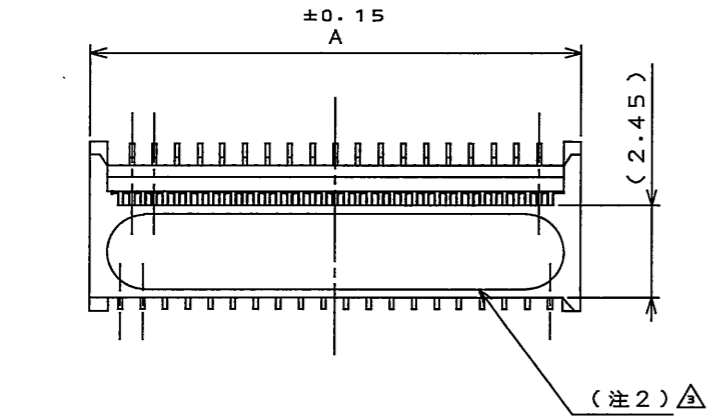
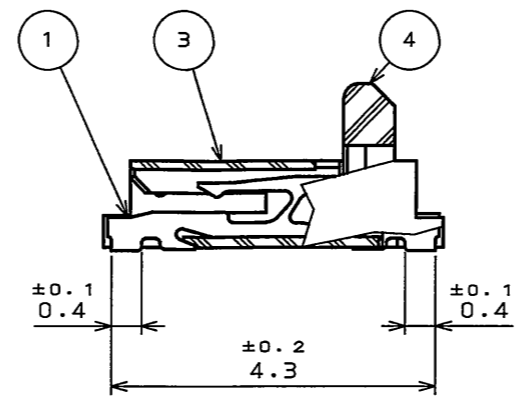


版数 REV.	年月日 DATE	DCN NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.
2	13.Feb.2007	061615	ADDED AND DELETED ITEMS		N.IKENAGA	T.KUDOU	K.IBARAKI
3	15.May.2007	062773	ADDED LOT NUMBER		N.IKENAGA	T.KUDOU	K.IBARAKI
4	3.Oct.2007	064016	ADDED ITEMS		N.IKENAGA	T.Kudo	K. Ibaraki

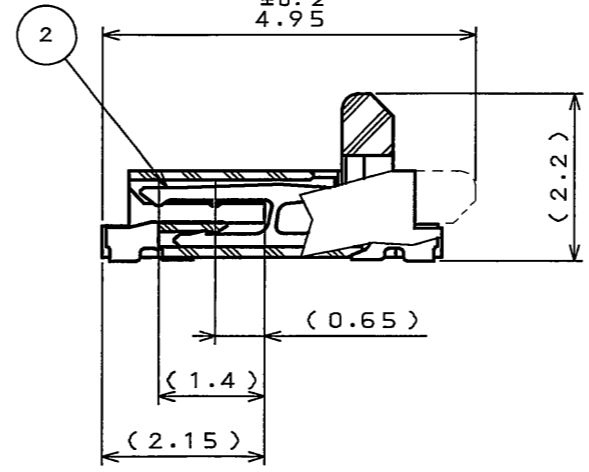
679901PS  
(DRAWING NO.)



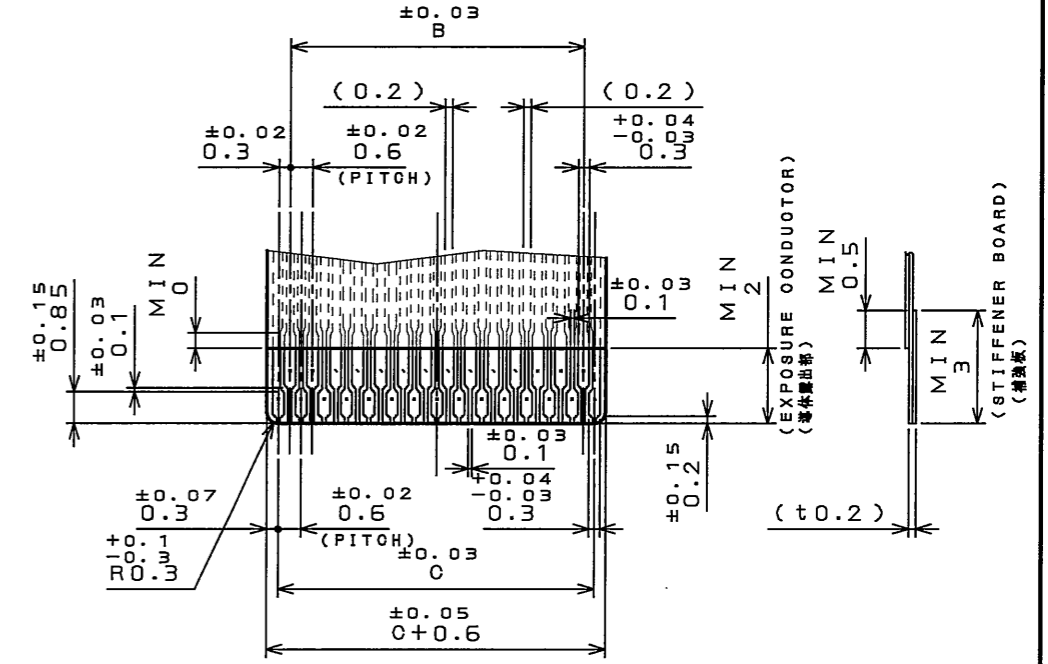
MATED CONDITION (REF.)  
嵌合状態図(参考)



SECT. A-A  
(SCALE 10:1)



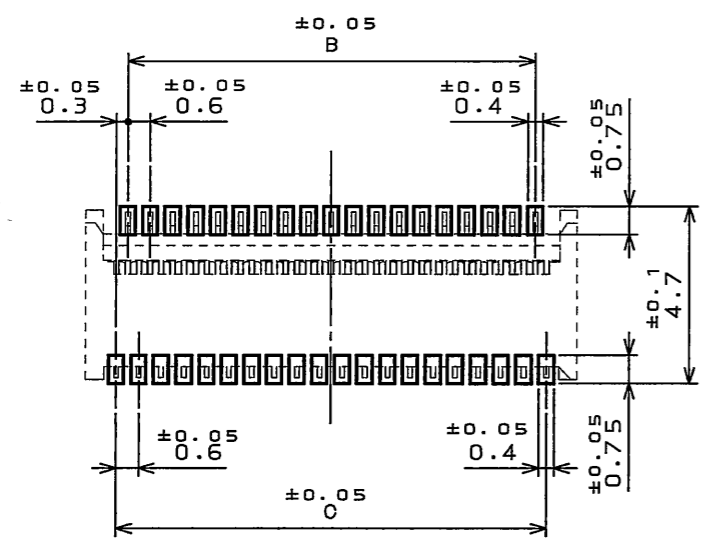
SECT. B-B  
(SCALE 10:1)



APPLICABLE F.P.C DIMENSION (REF.)  
適合FPC寸法(参考)  
(THICKNESS: 0.2 ± 0.03)

NOTE1. POLYIMIDE SHOULD BE USED AS A STIFFENER BOARD AND THERMOSETTING ADHESIVE SHOULD BE USED.  
BARE TRACES SHOULD BE GIVEN GOLD PLATING.  
NOTE2. LOT NUMBER IS MARKED ON THE TOP OF THE CONNECTOR.

注1. 適合FPCの補強板はポリイミドを使用し、接着剤は熱硬化性を使用すること。  
又、仕上げは金メッキのこと。  
注2. ロット番号がコネクタ上面部に表記されます。



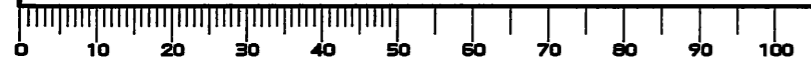
APPLICABLE P.C.B. DIMENSION (REF.)  
適合基板寸法(参考)

TABLE 1

NO. OF CONTACT	A	B	C
17	6.4	4.2	4.8
23	8.2	6.0	6.6
25	8.8	6.6	7.2
29	10.0	7.8	8.4
31	10.6	8.4	9.0
33	11.2	9.0	9.6
35	11.8	9.6	10.2
39	13.0	10.8	11.4
41	13.6	11.4	12.0
45	14.8	12.6	13.2
51	16.6	14.4	15.0

符号 NO.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL	仕上 FINISH	備考 REMARKS
4	ACTUATOR	1	GLASS FILLED NY		COLOR: BLACK UL94V-0
3	BASE INSULATOR	1	GLASS FILLED LCP		COLOR: BEIGE UL94V-0
2	CONTACT 2	$\frac{n-1}{2}$	COPPER ALLOY	SELECTIVE GOLD PLATING	
1	CONTACT 1	$\frac{n+1}{2}$	COPPER ALLOY	SELECTIVE GOLD PLATING	
仕様書(SPECIFICATION)		第1版(ORIGINAL DATE)		尺度(SCALE)	
JAGS-10358		31.Jul.2006		5:1	
J AHL-10358		製図 DR.		シリーズ(SERIES)	
				FB8	
公差(GENERAL TOLERANCE)		担当 CHK.		名称(TITLE)	
寸法(DIMENSION)		N.IKENAGA		FB8S***JA1	
角度(ANGLES)		査閲 APPD.		質量(MASS)	
. ±0.8		T.KUDOU		◎	
.X ±0.4		承認 APPD.			
.XX ±0.1		K.IBARAKI			
.XXX ±					
図面番号(DRAWING NO.)					
SJ106679					

DOF-0-212F(05.08)



SIZE A3